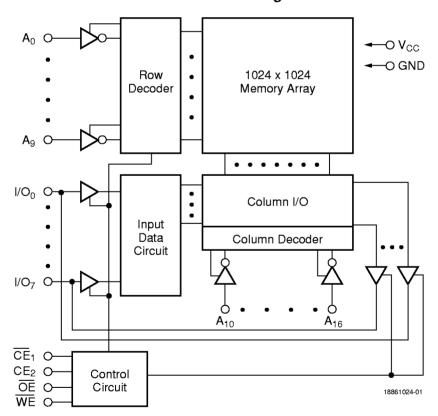
### Features

- High-speed: 90, 120 ns
- Ultra low DC operating current of 25 mA (max.)− CMOS Standby: 5 μA (Max.)
- Fully static operation
- All inputs and outputs directly compatible
- Three state outputs
- Ultra low data retention current (V<sub>CC</sub> = 1V)
- Single Power Supply voltage: 1.8V-2.2V
- Packages
  - 32-pin TSOP (Standard)
  - 32-pin STSOP

## Description

The V62C1881024 is a 1,048,576-bit static random-access memory organized as 131,072 words by 8 bits. It is built with MOSEL VITELIC's high performance CMOS process. Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures.

## Functional Block Diagram



### Device Usage Chart

Operating	Package	Package Outline		Access Time (ns)		wer	T	
Temperature Range	Т	s	90	120	L	LL	Temperature Mark	
0°C to 70 °C	•	•	•	•	•	•	Blank	
-40°C to +85°C	•	•	•			•	I	

## Pin Descriptions

### A<sub>0</sub>-A<sub>16</sub> Address Inputs

These 17 address inputs select one of the 128K x 8 bit segments in the RAM.

## CE<sub>1</sub>, CE<sub>2</sub> Chip Enable Inputs

CE<sub>1</sub> is active LOW and CE<sub>2</sub> is active HIGH. Both chip enables must be active to read from or write to the device. If either chip enable is not active, the device is deselected and is in a standby power mode. The I/O pins will be in the high-impedance state when deselected.

### OE Output Enable Input

The output enable input is active LOW. When  $\overline{OE}$  is LOW with  $\overline{CE}$  LOW and  $\overline{WE}$  HIGH, data of the selected memory allocation will be available on the I/O pins. When  $\overline{OE}$  is HIGH, the I/O pins will be in the high impedance state.

## WE Write Enable Input

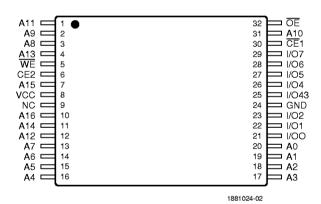
An active LOW input,  $\overline{WE}$  input controls read and write operations. When  $\overline{CE}$  and  $\overline{WE}$  inputs are both LOW, the data present on the I/O pins will be written into the selected memory location.

I/O<sub>0</sub>—I/O<sub>7</sub> Data Input and Data Output Ports
These 8 bidirectional ports are used to read data from and write data into the RAM.

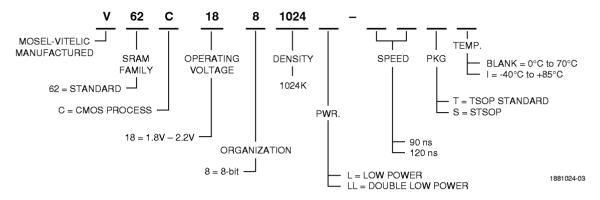
V<sub>CC</sub> Power Supply

GND Ground

### 32-PIN TSOP/STSOP



### Part Number Information



# Absolute Maximum Ratings (1)

Symbol	Parameter	Commercial	Industrial	Units
V <sub>CC</sub>	Supply Voltage	-0.5 to V <sub>CC</sub> +0.5	-0.5 to V <sub>CC</sub> +0.5	V
$V_N$	Input Voltage	-0.5 to +0.5	-0.5 to +0.5	V
V <sub>DQ</sub>	Input/Output Voltage Applied	V <sub>CC</sub> + 0.3	V <sub>CC</sub> + 0.3	V
T <sub>BIAS</sub>	Temperature Under Bias	-10 to +125	-65 to +135	°C
T <sub>STG</sub>	Storage Temperature	-55 to +125	-65 to +150	°C

### NOTE:

## Capacitance\*

 $T_A = 25^{\circ}C$ , f = 1.0MHz

Symbol	Parameter	Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$V_{IN} = 0V$	6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>I/O</sub> = 0V	8	pF

### NOTE:

1. This parameter is guaranteed and not tested.

### Truth Table

Mode	CE <sub>1</sub>	CE <sub>2</sub>	ŌĒ	WE	I/O Operation
Standby	Н	Х	Х	Х	High Z
Standby	х	L	х	Х	High Z
Output Disable	L	Н	Н	Н	High Z
Read	L	Н	L	Н	D <sub>OUT</sub>
Write	L	Н	Х	L	D <sub>IN</sub>

NOTE:

X = Don't Care, L = LOW, H = HIGH

<sup>1.</sup> Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

# **DC Electrical Characteristics** (over all temperature ranges, $V_{CC}$ = 2.0 $\pm$ 0.2V)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>CC</sub>	Power Supply Voltage		1.8		2.2	V
V <sub>IL</sub>	Input LOW Voltage <sup>(1,2)</sup>		-0.3	_	0.4	V
V <sub>IH</sub>	Input HIGH Voltage <sup>(1)</sup>		1.6	_	V <sub>CC</sub> +0.2	٧
I <sub>IL</sub>	Input Leakage Current	V <sub>CC</sub> = Max, V <sub>IN</sub> = 0V to V <sub>CC</sub>	-2	_	2	μΑ
I <sub>OL</sub>	Output Leakage Current	$V_{CC} = Max, \overline{CE}_1 = V_{IH}, V_{OUT} = 0V \text{ to } V_{CC}$	-2	_	2	μΑ
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min, I <sub>OL</sub> = 2.1mA	_	_	0.4	٧
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min, I <sub>OH</sub> = -1mA	1.6	_	_	٧

Symbol	Parameter		Power	Com. <sup>(4)</sup>	Ind. <sup>(4)</sup>	Units
I <sub>CC</sub>	Operating Power Supply Current, $\overline{CE}_1 = V_{ L}$ , $CE_2 = V_{ H}$ ,	READ	L	4	6	
	Output Open, V <sub>CC</sub> = Max., f = 0		LL	3	5	]
		WRITE	L	30	35	mA
			LL	25	30	]
I <sub>CC1</sub>	Average Operating Current, $\overline{CE}_1 = V_{ L}$ , $CE_2 = V_{ H}$ , Output Open, $V_{CC} = Max.$ , $f = f_{MAX}^{(3)}$			20	30	mA
I <sub>SB</sub>	TTL Standby Current		L	0.5	0.7	mA
	$\overline{CE}_1 \ge V_{IH}, CE_2 \le V_{IL}, V_{CC} = Max.$		LL	0.3	0.5	'''^
I <sub>SB1</sub>	$I_{SB1}$ CMOS Standby Current, $\overline{CE}_1 \ge V_{CC} - 0.2V$ , $CE_2 \le 0.2V$ ,	·	L	5	8	
	$V_{IN} \ge V_{CC} - 0.2V$ or $V_{IN} \le 0.2V$ , $V_{CC} = Max$ .		LL	1	2	μΑ

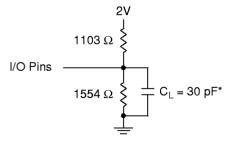
#### NOTES:

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2.  $V_{IL}$  (Min.) = -3.0V for pulse width < 20ns.
- $3. \quad f_{MAX} = 1/t_{RC}.$
- 4. Maximum values.

## **AC Test Conditions**

Input Pulse Levels	0 to 1.6V
Input Rise and Fall Times	5 ns
Timing Reference Levels	1.0V
Output Load	see below

## AC Test Loads and Waveforms



<sup>\*</sup> Includes scope and jig capacitance

1881024-04

# Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE: ANY CHANGE PERMITTED	CHANGING: STATE UNKNOWN
<b>&gt;</b>	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

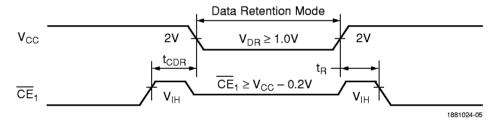
## Data Retention Characteristics

Symbol	Parameter		Power	Min.	Typ. <sup>(2)</sup>	Max.	Units
V <sub>DR</sub>	$\label{eq:continuous} \begin{array}{c} V_{CC} \text{ for Data Retention} & \overline{CE}_1 \geq V_{CC} - 0.2V, \ CE_2 \leq 0.2V, \\ V_{IN} \geq V_{CC} - 0.2V, \ \text{or } V_{IN} \leq 0.2V \end{array}$			2.0		3.6	٧
I <sub>CCDR</sub>	$I_{CCDR}$ Data Retention Current $\overline{CE}_1 \ge V_{DR} -0.2V$ , $CE_2 \le 0.2V$ ,	Com'l	L	_	1	3	μА
	$CE_1 \ge V_{DR} - 0.2V$ , $CE_2 \le 0.2V$ , $V_{IN} \ge V_{CC} - 0.2V$ , or $V_{IN} \le 0.2V$		LL	_	0.5	1	
	IN GG / IN	Ind.	L	_	_	5	
			LL	_	_	3	
t <sub>CDR</sub>	Chip Deselect to Data Retention Time			0	_		ns
t <sub>R</sub>	Operation Recovery Time (see Retention Waveform)			t <sub>RC</sub> <sup>(1)</sup>	_	_	ns

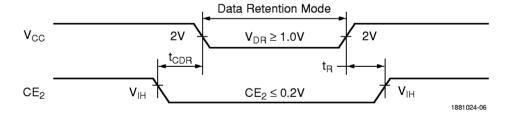
### NOTES:

 $t_{RC}$  = Read Cycle Time  $T_A$  = +25°C.

# Low $V_{CC}$ Data Retention Waveform (1) ( $\overline{CE}_1$ Controlled)



# Low V<sub>CC</sub> Data Retention Waveform (2) (CE<sub>2</sub> Controlled)



# AC Electrical Characteristics

(over all temperature ranges)

# **Read Cycle**

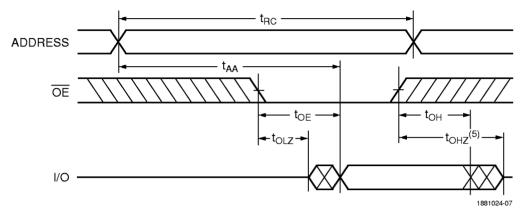
Parameter		9	0	1:		
Name	Parameter	Min.	Max.	Min.	Max.	Unit
t <sub>RC</sub>	Read Cycle Time	90	_	120	_	ns
t <sub>AA</sub>	Address Access Time	_	90	_	120	ns
t <sub>ACS1</sub>	Chip Enable Access Time	_	90	_	120	ns
t <sub>ACS2</sub>	Chip Enable Access Time	_	90	_	120	ns
t <sub>OE</sub>	Output Enable to Output Valid	_	50	_	65	ns
t <sub>CLZ1</sub>	Chip Enable to Output in Low Z	10	_	15	_	ns
t <sub>CLZ2</sub>	Chip Enable to Output in Low Z	10	_	15	_	ns
t <sub>OLZ</sub>	Output Enable to Output in Low Z	10	_	10	_	ns
t <sub>CHZ</sub>	Chip Disable to Output in High Z	0	35	0	40	ns
t <sub>OHZ</sub>	Output Disable to Output in High Z	0	35	0	40	ns
t <sub>OH</sub>	Output Hold from Address Change	10	_	10	_	ns
t <sub>PU</sub>	Chip Enable to Power Up Time	0	_	0	_	ns
t <sub>PD</sub>	Chip Enable to Power Down Time	_	90	_	120	ns

# **Write Cycle**

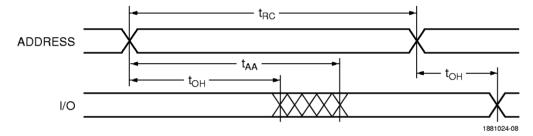
Parameter			90	1:		
Name	Parameter	Min.	Max.	Min.	Max.	Unit
t <sub>WC</sub>	Write Cycle Time	90	_	120	_	ns
t <sub>CW1</sub>	Chip Enable to End of Write	75	_	100	_	ns
t <sub>CW2</sub>	Chip Enable to End of Write	75	_	100	_	ns
t <sub>AS</sub>	Address Setup Time	0	_	0	_	ns
t <sub>AW</sub>	Address Valid to End of Write	75	_	100	_	ns
t <sub>WP</sub>	Write Pulse Width	70	_	90	_	ns
t <sub>WR</sub>	Write Recovery Time	0	_	0	_	ns
t <sub>WHZ</sub>	Write to Output High-Z	0	40	0	50	ns
t <sub>WLZ</sub>	Write to Output Low Z	10	_	15	_	ns
t <sub>DW</sub>	Data Setup to End of Write	40	_	50	_	ns
t <sub>DH</sub>	Data Hold from End of Write	0	_	0	_	ns

# Switching Waveforms (Read Cycle)

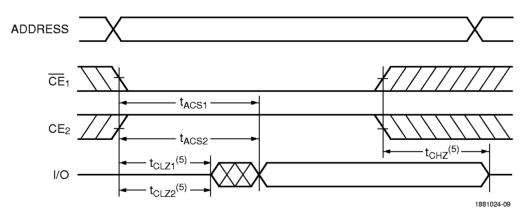
# Read Cycle 1<sup>(1, 2)</sup>



# Read Cycle 2<sup>(1, 2, 4)</sup>



# Read Cycle 3<sup>(1, 3, 4)</sup>

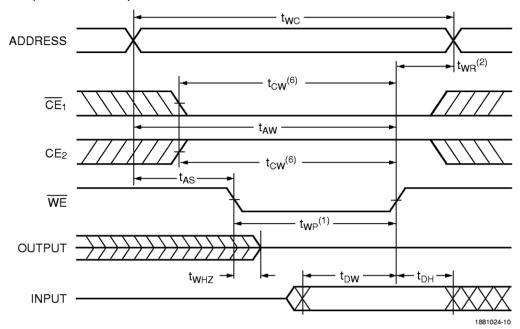


## NOTES:

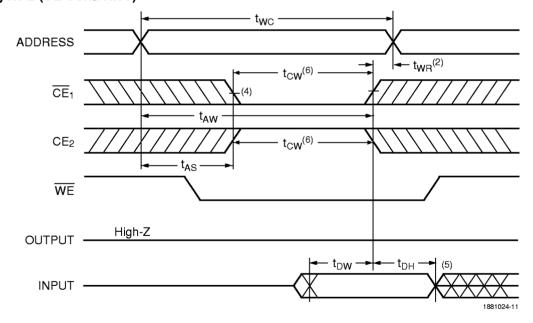
- 3.
- $\overline{OE} = V_{IL}$ . 4.
- Transition is measured  $\pm 500$ mV from steady state with  $C_L = 5$ pF. This parameter is guaranteed and not 100% tested.

## Switching Waveforms (Write Cycle)

## Write Cycle 1 (WE Controlled)(4)



# Write Cycle 2 (CE Controlled)(4)



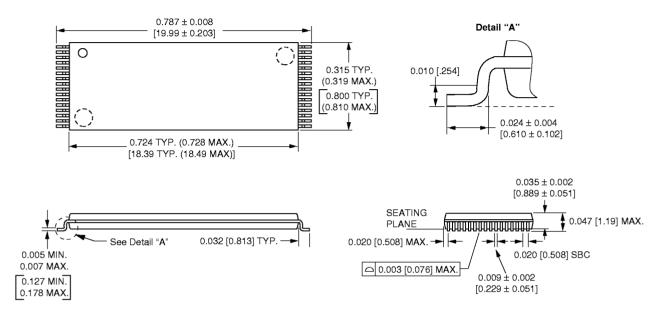
### NOTES:

- 1. The internal write time of the memory is defined by the overlap of \(\overline{CE}\_1\) and \(\overline{CE}\_2\) active and \(\overline{WE}\) low. All signals must be active to initiate and any one signal can terminate a write by going inactive. The data input setup and hold timing should be referenced to the second transition edge of the signal that terminates the write.
- 2. twB is measured from the earlier of CE<sub>1</sub> or WE going high, or CE<sub>2</sub> going LOW at the end of the write cycle.
- 3. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
- 4.  $\overline{OE} = V_{IL}$  or  $V_{IH}$ . However it is recommended to keep  $\overline{OE}$  at  $V_{IH}$  during write cycle to avoid bus contention.
- If CE<sub>1</sub> is LOW and CE<sub>2</sub> is HIGH during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
- 6.  $t_{CW}$  is measured from  $\overline{CE}_1$  going low or  $CE_2$  going HIGH to the end of write.

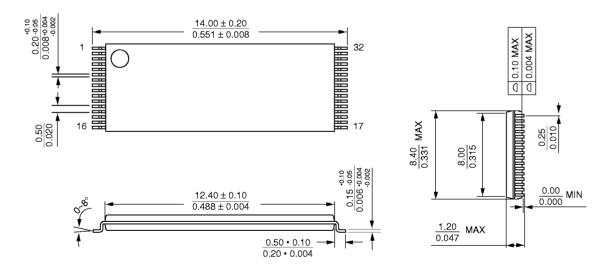
# Package Diagrams

## 32-Pin TSOP (Standard)

Units in inches [mm]



### 32-Pin STSOP



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